

PMP5201V; PMP5201G; PMP5201Y

PNP/PNP matched double transistors

Rev. 03 — 28 August 2009

Product data sheet

1. Product profile

1.1 General description

PNP/PNP matched double transistors in small Surface-Mounted Device (SMD) plastic packages. The transistors in the SOT666 and SOT363 (SC-88) packages are fully isolated internally.

Table 1. Product overview

| Type number | Package | | PNP/PNP h_{FE1}/h_{FE2} 0.95 complement | NPN/NPN complement |
|-------------|---------|--------|--|-----------------------|
| | NXP | JEITA | | |
| PMP5201V | SOT666 | - | PMP5501V | PMP4201V |
| PMP5201G | SOT353 | SC-88A | PMP5501G | PMP4201G |
| PMP5201Y | SOT363 | SC-88 | PMP5501Y | PMP4201Y |

1.2 Features

- Current gain matching
- Base-emitter voltage matching
- Common emitter configuration for SOT353 types
- Application-optimized pinout

1.3 Applications

- Current mirror
- Differential amplifier

1.4 Quick reference data

Table 2. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|---------------------------|-----------------------------------|-----|-----|------|------|
| Per transistor | | | | | | |
| V_{CE0} | collector-emitter voltage | open base | - | - | -45 | V |
| I_C | collector current | | - | - | -100 | mA |
| h_{FE} | DC current gain | $V_{CE} = -5$ V; $I_C = -2$ mA | 200 | 290 | 450 | |



Table 2. Quick reference data ...continued

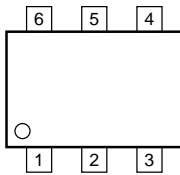
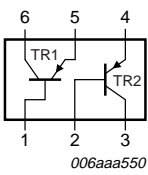
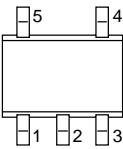
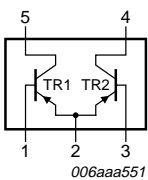
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------|-------------------|---|----------|-----|-----|------|
| Per device | | | | | | |
| h_{FE1}/h_{FE2} | h_{FE} matching | $V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$ | [1] 0.98 | 1 | - | |
| $V_{BE1}-V_{BE2}$ | V_{BE} matching | $V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$ | [2] - | - | 2 | mV |

[1] The smaller of the two values is taken as the numerator.

[2] The smaller of the two values is subtracted from the larger value.

2. Pinning information

Table 3. Pinning

| Pin | Description | Simplified outline | Symbol |
|-----------------------|------------------|--|--|
| SOT666; SOT363 | | | |
| 1 | base TR1 |  <p>001aab555</p> |  <p>006aaa550</p> |
| 2 | base TR2 | | |
| 3 | collector TR2 | | |
| 4 | emitter TR2 | | |
| 5 | emitter TR1 | | |
| 6 | collector TR1 | | |
| SOT353 | | | |
| 1 | base TR1 |  |  <p>006aaa551</p> |
| 2 | emitter TR1, TR2 | | |
| 3 | base TR2 | | |
| 4 | collector TR2 | | |
| 5 | collector TR1 | | |

3. Ordering information

Table 4. Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| PMP5201V | - | plastic surface-mounted package; 6 leads | SOT666 |
| PMP5201G | SC-88A | plastic surface-mounted package; 5 leads | SOT353 |
| PMP5201Y | SC-88 | plastic surface-mounted package; 6 leads | SOT363 |

4. Marking

Table 5. Marking codes

| Type number | Marking code ^[1] |
|-------------|-----------------------------|
| PMP5201V | EC |
| PMP5201G | R5* |
| PMP5201Y | S9* |

- [1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------------------|---------------------------|----------------------------------|-------------------|------|------|
| Per transistor | | | | | |
| V_{CBO} | collector-base voltage | open emitter | - | -50 | V |
| V_{CEO} | collector-emitter voltage | open base | - | -45 | V |
| V_{EBO} | emitter-base voltage | open collector | - | -5 | V |
| I_C | collector current | | - | -100 | mA |
| I_{CM} | peak collector current | single pulse; $t_p \leq 1$ ms | - | -200 | mA |
| P_{tot} | total power dissipation | $T_{amb} \leq 25$ °C | | | |
| | SOT666 | | ^{[1][2]} | 200 | mW |
| | SOT353 | | ^[1] | 200 | mW |
| | SOT363 | | ^[1] | 200 | mW |
| Per device | | | | | |
| P_{tot} | total power dissipation | $T_{amb} \leq 25$ °C | | | |
| | SOT666 | | ^{[1][2]} | 300 | mW |
| | SOT353 | | ^[1] | 300 | mW |
| | SOT363 | | ^[1] | 300 | mW |
| T_j | junction temperature | | - | 150 | °C |
| T_{amb} | ambient temperature | | -65 | +150 | °C |
| T_{stg} | storage temperature | | -65 | +150 | °C |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

6. Thermal characteristics

Table 7. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|---|-------------|--------|-----|-----|------|
| Per transistor | | | | | | |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | | | | |
| | SOT666 | | [1][2] | - | 625 | K/W |
| | SOT353 | | [1] | - | 625 | K/W |
| | SOT363 | | [1] | - | 625 | K/W |
| Per device | | | | | | |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | | | | |
| | SOT666 | | [1][2] | - | 416 | K/W |
| | SOT353 | | [1] | - | 416 | K/W |
| | SOT363 | | [1] | - | 416 | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

7. Characteristics

Table 8. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|--------------------------------------|--|-----|------|------|---------------|
| Per transistor | | | | | | |
| I_{CBO} | collector-base cut-off current | $V_{CB} = -30\text{ V};$ $I_E = 0\text{ A}$ | - | - | -15 | nA |
| | | $V_{CB} = -30\text{ V};$ $I_E = 0\text{ A};$ $T_j = 150\text{ }^{\circ}\text{C}$ | - | - | -5 | μA |
| I_{EBO} | emitter-base cut-off current | $V_{EB} = -5\text{ V};$ $I_C = 0\text{ A}$ | - | - | -100 | nA |
| h_{FE} | DC current gain | $V_{CE} = -5\text{ V};$ $I_C = -10\text{ }\mu\text{A}$ | - | 250 | - | |
| | | $V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$ | 200 | 290 | 450 | |
| V_{CEsat} | collector-emitter saturation voltage | $I_C = -10\text{ mA};$ $I_B = -0.5\text{ mA}$ | - | -50 | -200 | mV |
| | | $I_C = -100\text{ mA};$ $I_B = -5\text{ mA}$ | - | -200 | -400 | mV |
| V_{BEsat} | base-emitter saturation voltage | $I_C = -10\text{ mA};$ $I_B = -0.5\text{ mA}$ | [1] | -760 | - | mV |
| | | $I_C = -100\text{ mA};$ $I_B = -5\text{ mA}$ | [1] | -920 | - | mV |

Table 8. Characteristics ...continued
 $T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

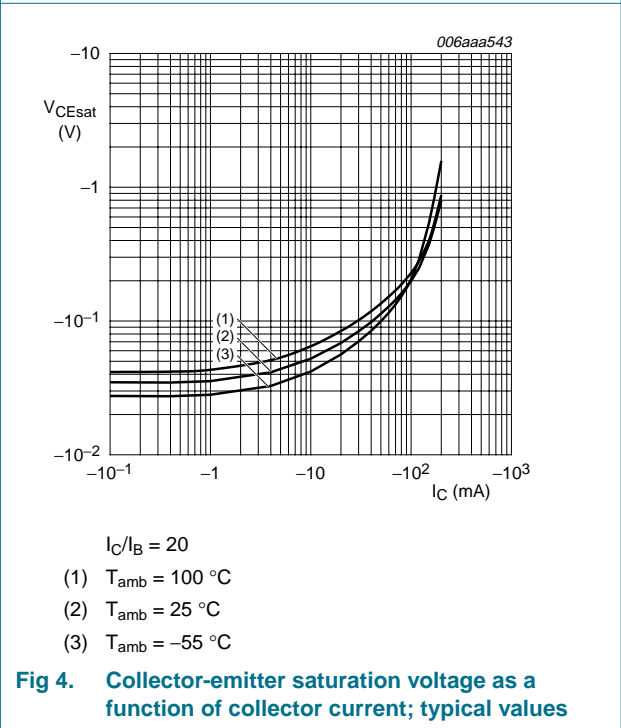
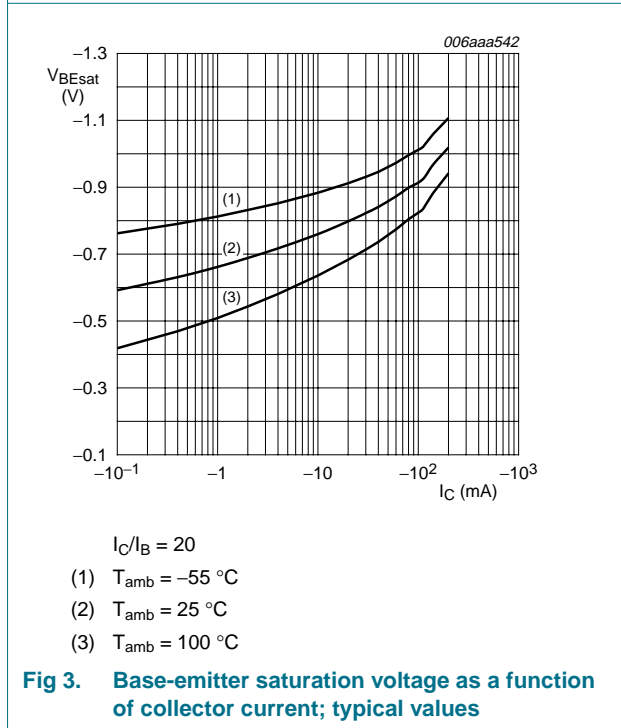
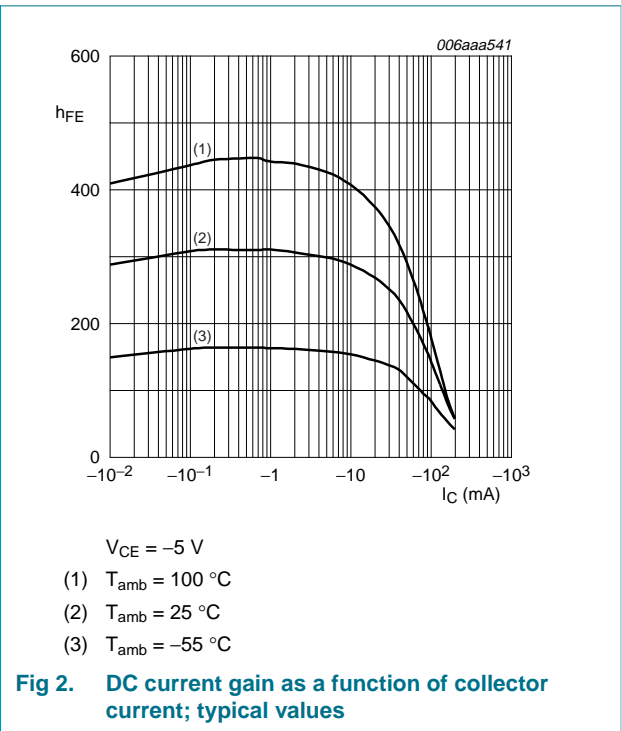
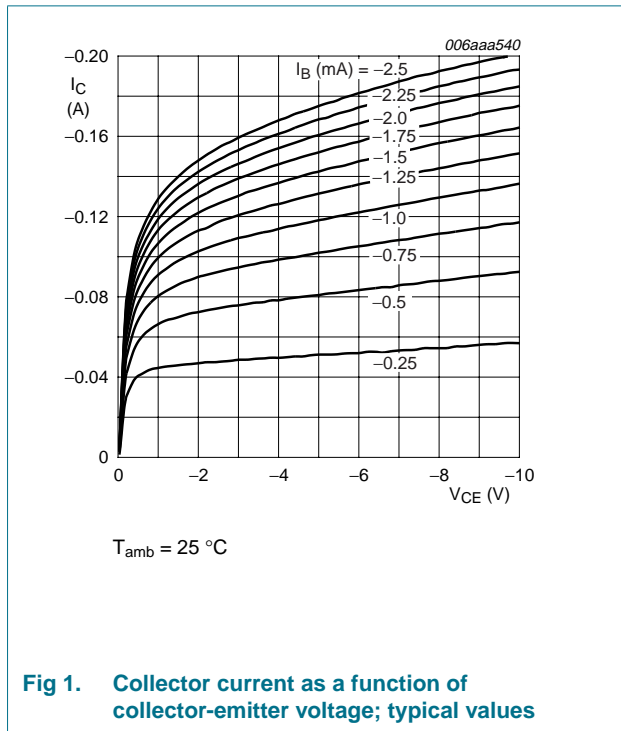
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------|-----------------------|---|----------|------|------|------|
| V_{BE} | base-emitter voltage | $V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$ | [2] -600 | -650 | -700 | mV |
| | | $V_{CE} = -5\text{ V};$ $I_C = -10\text{ mA}$ | [2] - | - | -760 | mV |
| C_c | collector capacitance | $V_{CB} = -10\text{ V};$ $I_E = i_e = 0\text{ A};$ $f = 1\text{ MHz}$ | - | - | 2.2 | pF |
| C_e | emitter capacitance | $V_{EB} = -0.5\text{ V};$ $I_C = i_c = 0\text{ A};$ $f = 1\text{ MHz}$ | - | 10 | - | pF |
| f_T | transition frequency | $V_{CE} = -5\text{ V};$ $I_C = -10\text{ mA};$ $f = 100\text{ MHz}$ | 100 | 175 | - | MHz |
| NF | noise figure | $V_{CE} = -5\text{ V};$ $I_C = -0.2\text{ mA};$ $R_S = 2\text{ k}\Omega;$ $f = 10\text{ Hz to}$ 15.7 kHz | - | 1.6 | - | dB |
| | | $V_{CE} = -5\text{ V};$ $I_C = -0.2\text{ mA};$ $R_S = 2\text{ k}\Omega;$ $f = 1\text{ kHz};$ $B = 200\text{ Hz}$ | - | 3.1 | - | dB |
| Per device | | | | | | |
| h_{FE1}/h_{FE2} | h_{FE} matching | $V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$ | [3] 0.98 | 1 | - | |
| $V_{BE1}-V_{BE2}$ | V_{BE} matching | $V_{CE} = -5\text{ V};$ $I_C = -2\text{ mA}$ | [4] - | - | 2 | mV |

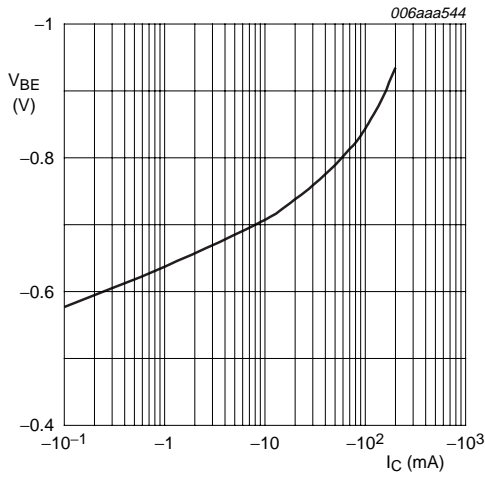
[1] V_{BEsat} decreases by about 1.7 mV/K with increasing temperature.

[2] V_{BE} decreases by about 2 mV/K with increasing temperature.

[3] The smaller of the two values is taken as the numerator.

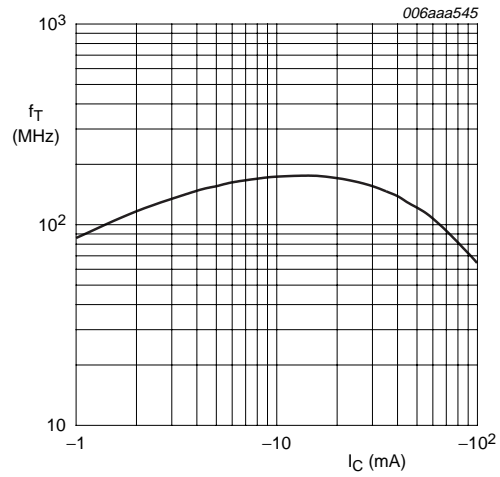
[4] The smaller of the two values is subtracted from the larger value.





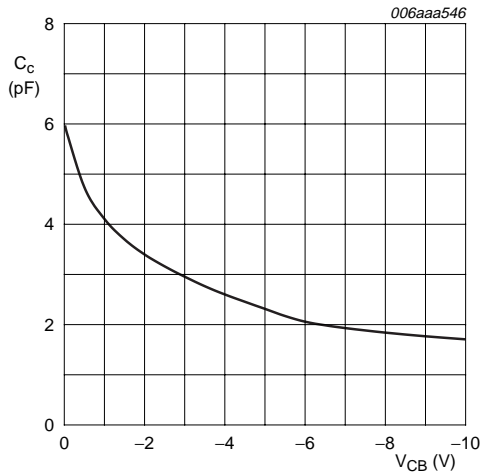
$V_{CE} = -5$ V; $T_{amb} = 25$ °C

Fig 5. Base-emitter voltage as a function of collector current; typical values



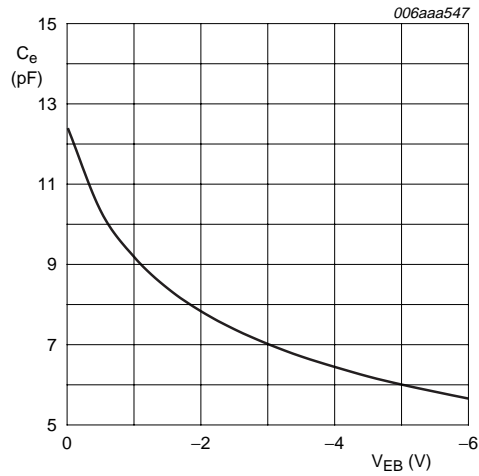
$V_{CE} = -5$ V; $T_{amb} = 25$ °C

Fig 6. Transition frequency as a function of collector current; typical values



$f = 1$ MHz; $T_{amb} = 25$ °C

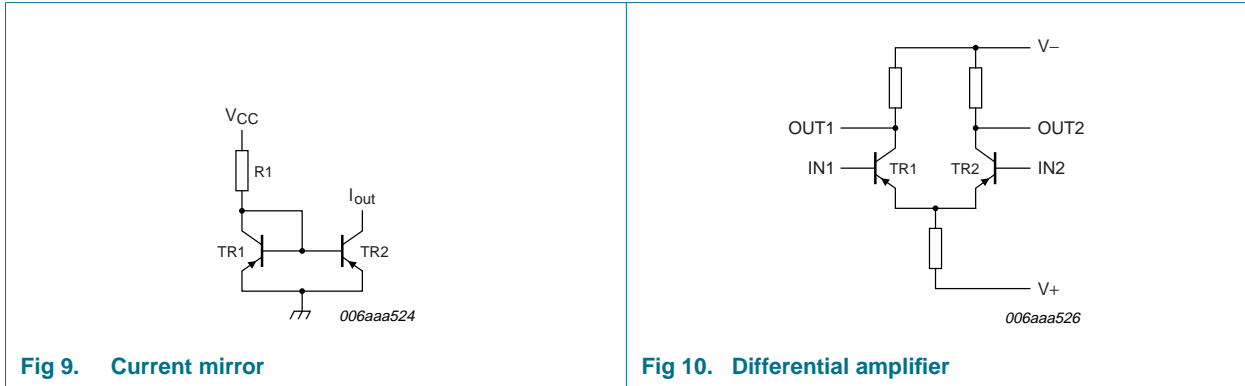
Fig 7. Collector capacitance as a function of collector-base voltage; typical values



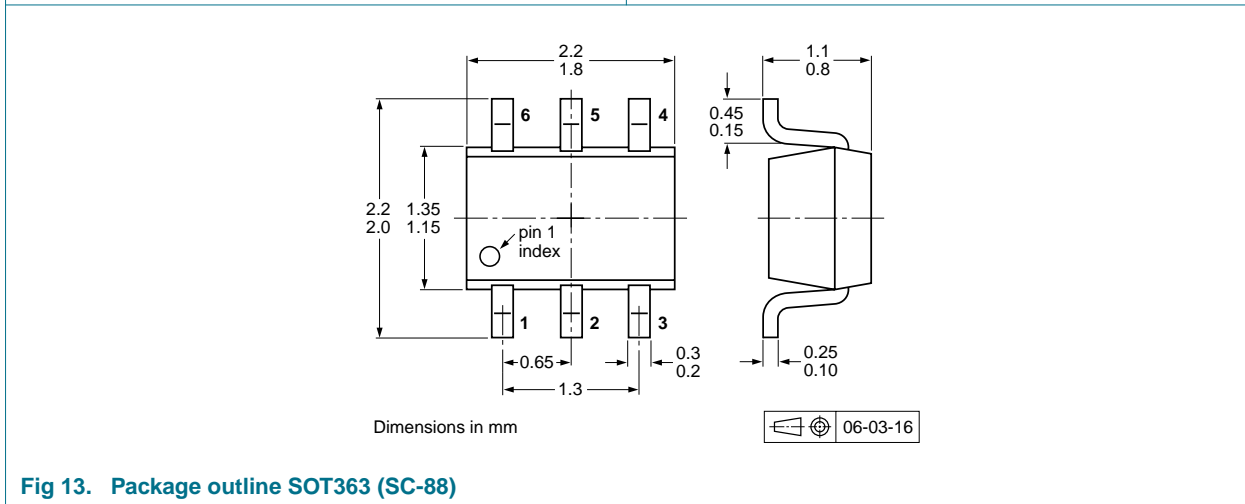
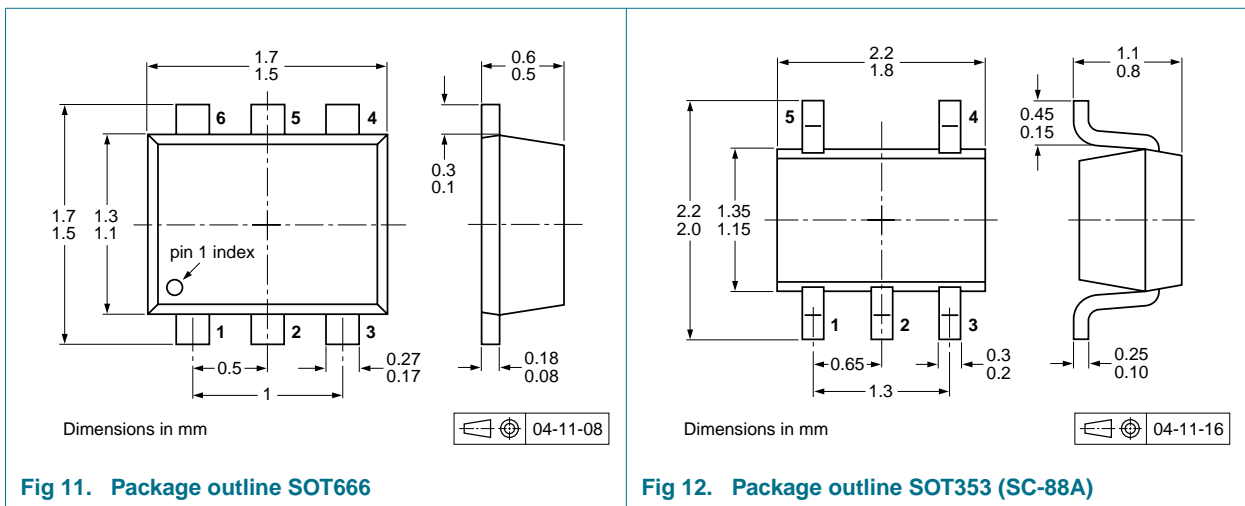
$f = 1$ MHz; $T_{amb} = 25$ °C

Fig 8. Emitter capacitance as a function of emitter-base voltage; typical values

8. Application information



9. Package outline



10. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

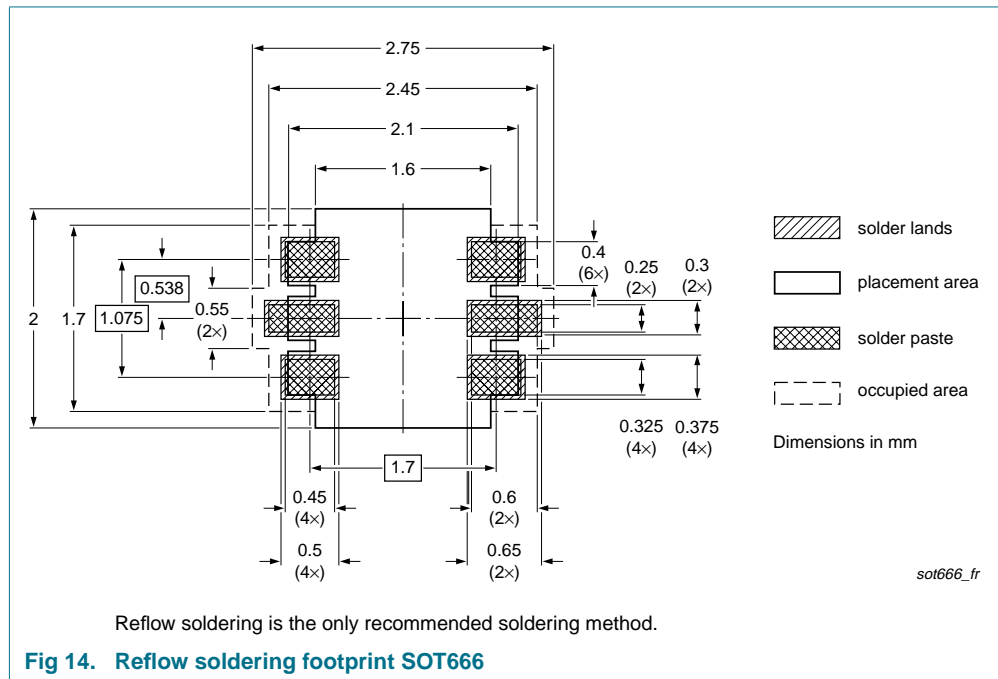
| Type number | Package | Description | Packing quantity | | | |
|-------------|---------|---|------------------|------|------|-------|
| | | | 3000 | 4000 | 8000 | 10000 |
| PMP5201V | SOT666 | 2 mm pitch, 8 mm tape and reel | - | - | -315 | - |
| | | 4 mm pitch, 8 mm tape and reel | - | -115 | - | - |
| PMP5201G | SOT353 | 4 mm pitch, 8 mm tape and reel | -115 | - | - | -135 |
| PMP5201Y | SOT363 | 4 mm pitch, 8 mm tape and reel; T1 ^[2] | -115 | - | - | -135 |
| | | 4 mm pitch, 8 mm tape and reel; T2 ^[3] | -125 | - | - | -165 |

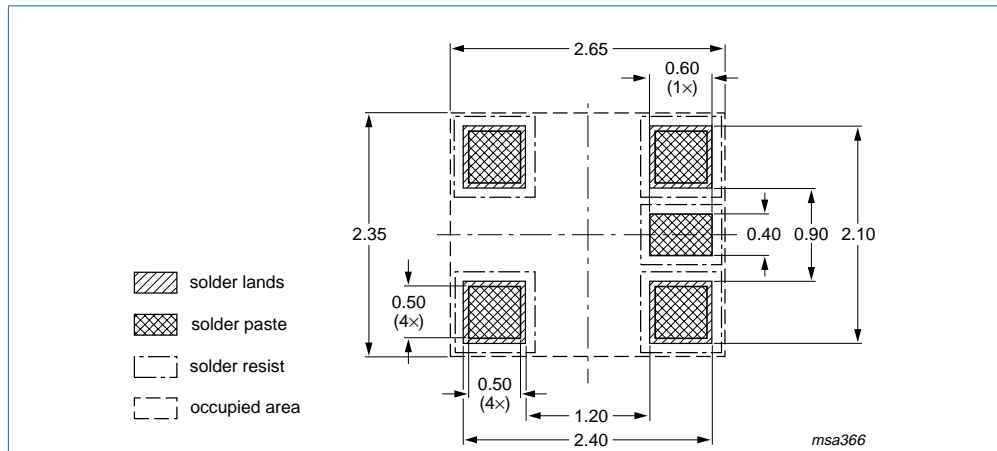
[1] For further information and the availability of packing methods, see [Section 14](#).

[2] T1: normal taping

[3] T2: reverse taping

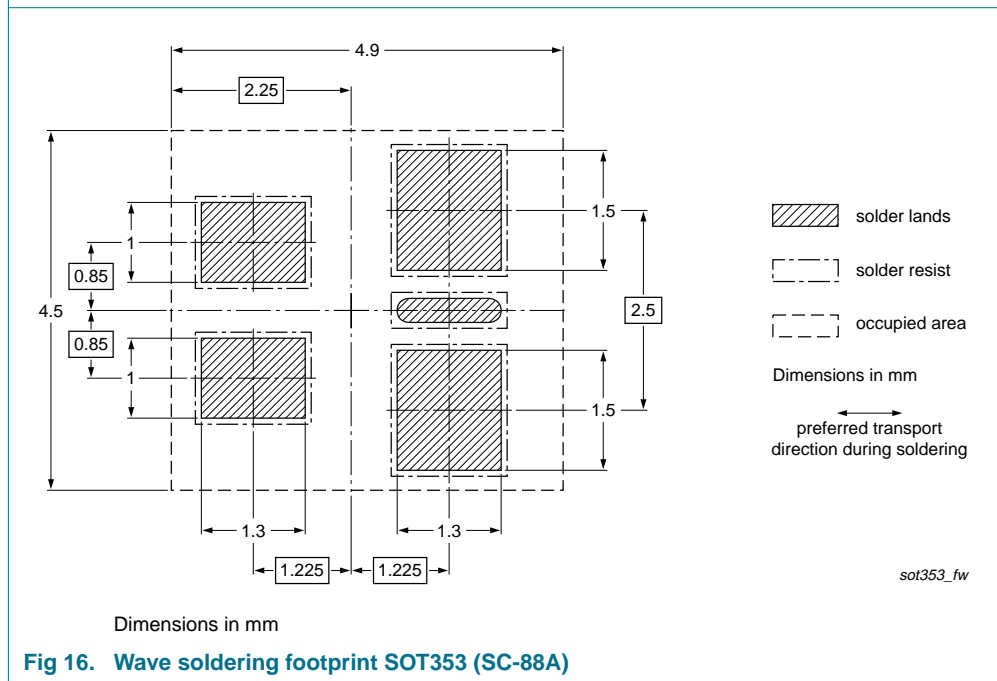
11. Soldering





Dimensions in mm

Fig 15. Reflow soldering footprint SOT353 (SC-88A)



Dimensions in mm

Fig 16. Wave soldering footprint SOT353 (SC-88A)

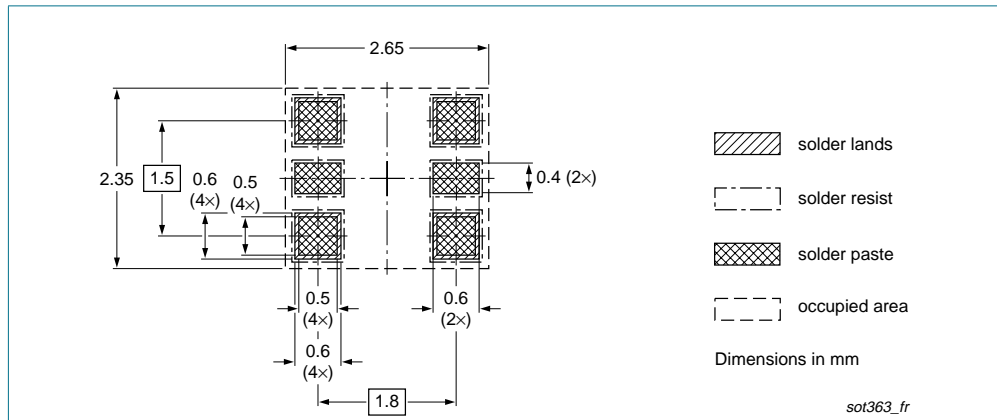


Fig 17. Reflow soldering footprint SOT363 (SC-88)

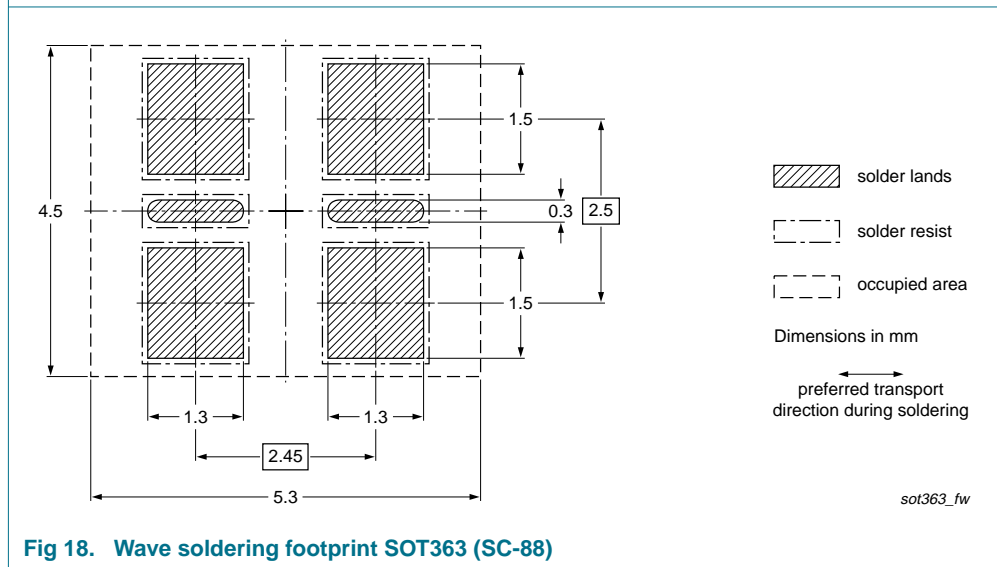


Fig 18. Wave soldering footprint SOT363 (SC-88)

12. Revision history

Table 10. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|----------------|--|--------------------|---------------|----------------|
| PMP5201V_G_Y_3 | 20090828 | Product data sheet | - | PMP5201V_G_Y_2 |
| Modifications: | <ul style="list-style-type: none"> • This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content. • Figure 14 "Reflow soldering footprint SOT666": updated • Figure 16 "Wave soldering footprint SOT353 (SC-88A)": updated • Figure 17 "Reflow soldering footprint SOT363 (SC-88)": updated • Figure 18 "Wave soldering footprint SOT363 (SC-88)": updated | | | |
| PMP5201V_G_Y_2 | 20060914 | Product data sheet | - | PMP5201G_Y_1 |
| PMP5201G_Y_1 | 20060214 | Product data sheet | - | - |

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13.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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15. Contents

| | | |
|-----------|--|-----------|
| 1 | Product profile | 1 |
| 1.1 | General description | 1 |
| 1.2 | Features | 1 |
| 1.3 | Applications | 1 |
| 1.4 | Quick reference data | 1 |
| 2 | Pinning information | 2 |
| 3 | Ordering information | 2 |
| 4 | Marking | 3 |
| 5 | Limiting values | 3 |
| 6 | Thermal characteristics | 4 |
| 7 | Characteristics | 4 |
| 8 | Application information | 8 |
| 9 | Package outline | 8 |
| 10 | Packing information | 9 |
| 11 | Soldering | 9 |
| 12 | Revision history | 12 |
| 13 | Legal information | 13 |
| 13.1 | Data sheet status | 13 |
| 13.2 | Definitions | 13 |
| 13.3 | Disclaimers | 13 |
| 13.4 | Trademarks | 13 |
| 14 | Contact information | 13 |
| 15 | Contents | 14 |

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